

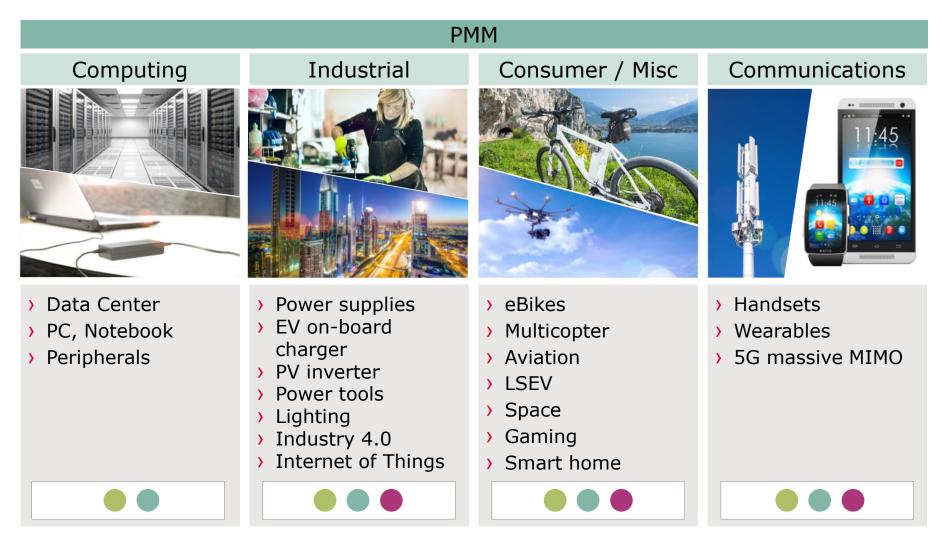
## IFX Day 2018 Andreas Urschitz Division President Power Management & Multimarket

London, 12 June 2018



# PMM's growth is built on many applications from different sectors in power and non-power





AC-DCDC-DCRF and sensors (non-power)



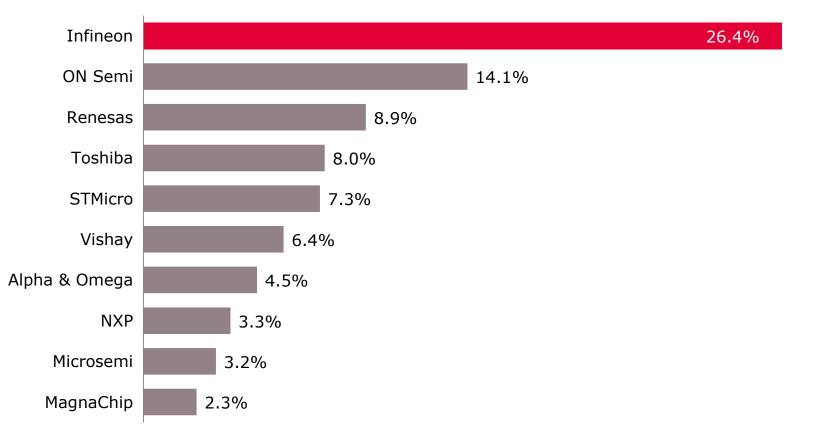
## PMM – Power



## PMM is the undisputed market leader in power MOSFETs







Source: Based on or includes content supplied by IHS Markit, Technology Group, "Power Semiconductor Discretes & Modules Report", August 2017; incl. automotive MOSFETs

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## Three strategic levers to outgrow the power semiconductor market







#### Strengthen core

- Complement technology leadership and #1 position in CoolMOS<sup>™</sup> and OptiMOS<sup>™</sup> with next-generation WBG power semis (CoolGaN<sup>™</sup>, CoolSiC<sup>™</sup>)
- Continuously increase scale leadership with 300 mm
- Exploit scale in R&D

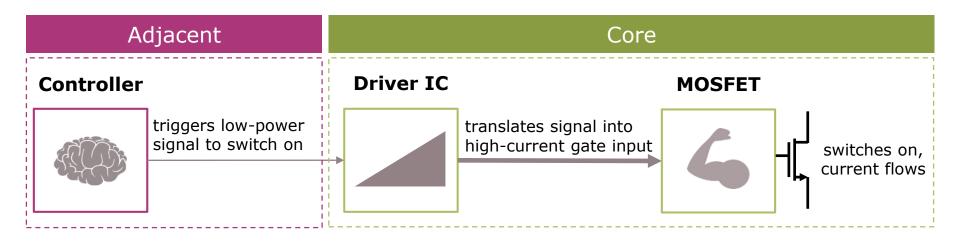
#### Grow in adjacent fields

- Complement core (= switch and driver ICs) by adding further (digital) power management ICs
- Grow into adjacent markets such as class D audio amplifiers or PoL in telecom and data center

#### Broaden scope to new applications

 System understanding and strong R&D force allow us to enter emerging power applications like AI data center, wireless power, EV on-board charger, infrastructure and LSEV Technology leadership in MOSFETs and digital power: highest efficiency and power density





#### Power management solutions reduce TCO







#### More efficient semiconductors

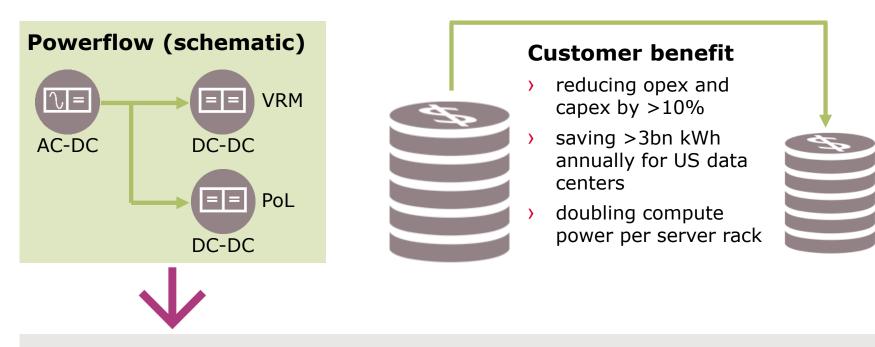
- lower power consumption
- > lower opex

#### **Higher power-density**

- > more compact system designs
- > lower capex

Highly differentiating solution for data center enables significant opex and capex reduction





#### Infineon-enabled optimization of data center powerflow – examples:



**CoolGaN™** allows for 2x output power in a given slot size and thus frees up space for the backup battery in more efficient architecture.

Benchmark **digital power solutions** including fully integrated PoL devices: highest efficiency, highest power density; supporting latest processor technologies.

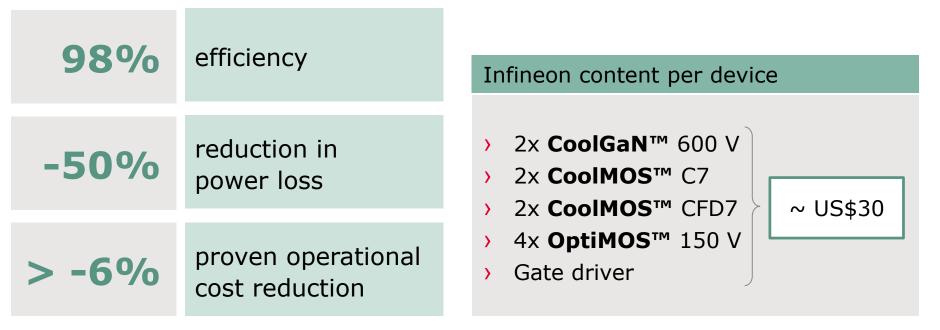


## AC-DC power supply by Eltek using CoolGaN<sup>™</sup>



#### Eltek "Flatpack2 SHE"

- > 3 kW / 48 V
- Fixed and wireless telecom applications
- > Size: 4.25 x 1.61 x 13 inch<sup>3</sup>
- > Weight: 4.5 lbs
- High power density: 33 W/inch<sup>3</sup>



## Server eco-system is supported by PMM's various DC-DC solutions





### Data center market trends

Increasing memory and processing power

Adoption of AI drives high-end analytics and data management

Expanding CPU supplier base: AMD, IBM, NVIDIA, ARM, Intel etc.

Hyperscale users invest in proprietary processor designs (e.g. Google) Saving space is a key requirement and a focus of product development



**Digital controllers** with flexible communications interface



#### Integrated power stages and iPoL

for high power density

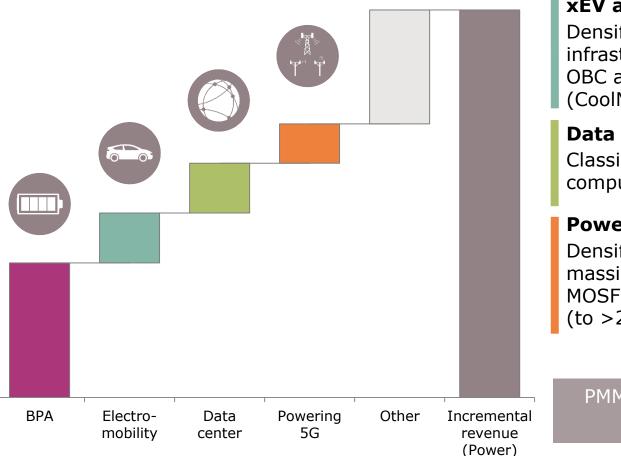


\* devices per server

PMM's mid-term growth in power is strongly driven by several high-growth applications



Composition of incremental € revenue over five year planning horizon by application



#### **Battery-powered applications**

E.g. power tools, consumer devices, robots and drones

#### **xEV** and **LSEV**

Densification of charging infrastructure; power semis for OBC and battery switch (CoolMOS<sup>™</sup>)

#### Data center

Classical data centers and highcomputing data centers for AI

#### Powering 5G

Densification of infrastructure; massive MIMO to drive power MOSFET content by a factor of 5 (to >250 pieces per system)

PMM power's trendline growth:  $\sim 9\%$ 



### Key take-aways – PMM Power

PMM is the undisputed market and technology leader in power MOSFETs and will **leverage scale advantages** in R&D and manufacturing.

PMM will **unlock further growth potential** with digital power management ICs and by addressing adjacent power applications.

PMM is excellently positioned in future-proof trends and will **continue to outgrow the market** going forward.



## PMM – RF and Sensing

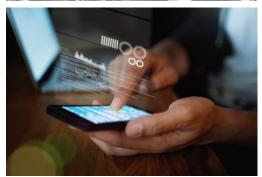


## RF and Sensing: Existing core competencies help seize additional growth opportunities



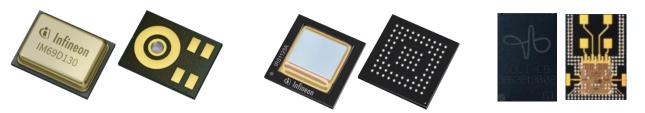






#### Strengthen core

- Technology leadership in key sensing technologies:
  - MEMS: XENSIV<sup>™</sup> silicon microphone
  - 3D ToF imaging: REAL3™
  - RF: 60 GHz radar for gesture sensing

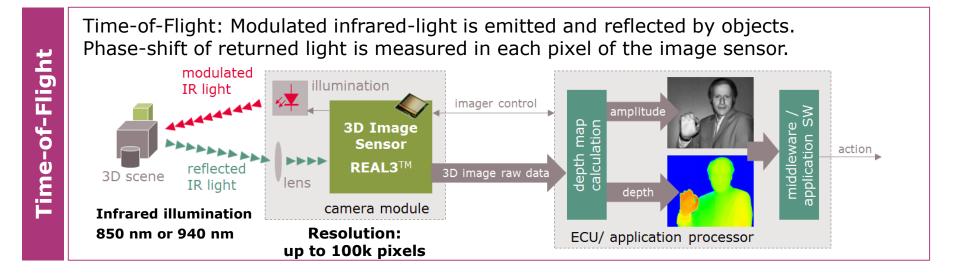


#### Grow in adjacent fields and address new markets

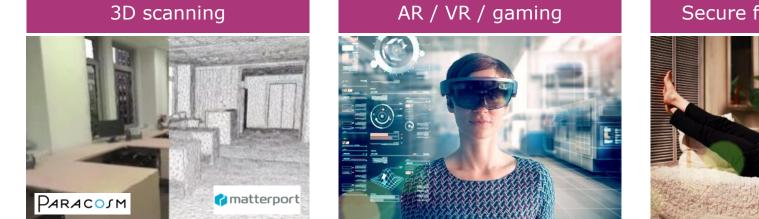
- Leverage technological capabilities to tap into adjacent sensor use cases (e.g. MEMS-based pressure sensors)
- > Address new markets with high growth potential
  - Human-machine interaction
  - 3D face recognition
  - 5G mmWave and sub-6-GHz for user equipment and basestations

## Leading base technologies for sensor solutions: Time-of-Flight





#### Examples of uses cases enabled by Time-of-Flight technology



#### Secure face recognition



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## RF and Sensing devices enable new services and will shape the way we live and work





Augmented Reality



Voice-controlled devices

Various use cases are enabled by a small set of versatile core technologies



Commercial and consumer multicopters



Gesture control



#### Smart streetlights



Industrial robotics



### Key take-aways – PMM RF and Sensing

PMM will **leverage its technology leadership** in MEMS microphones and broaden the success in smartphones to new emerging applications.

Strong core in MEMS is complemented by leading 3D Time-of-Flight imaging and radar technology, enabling **leadership in intuitive sensing and HMI**.

PMM's sensor portfolio emulates human senses, thus enabling attractive new uses cases with **significant revenue potential**.

PMM RFS is set to deliver ~9% revenue CAGR over five year planning horizon.

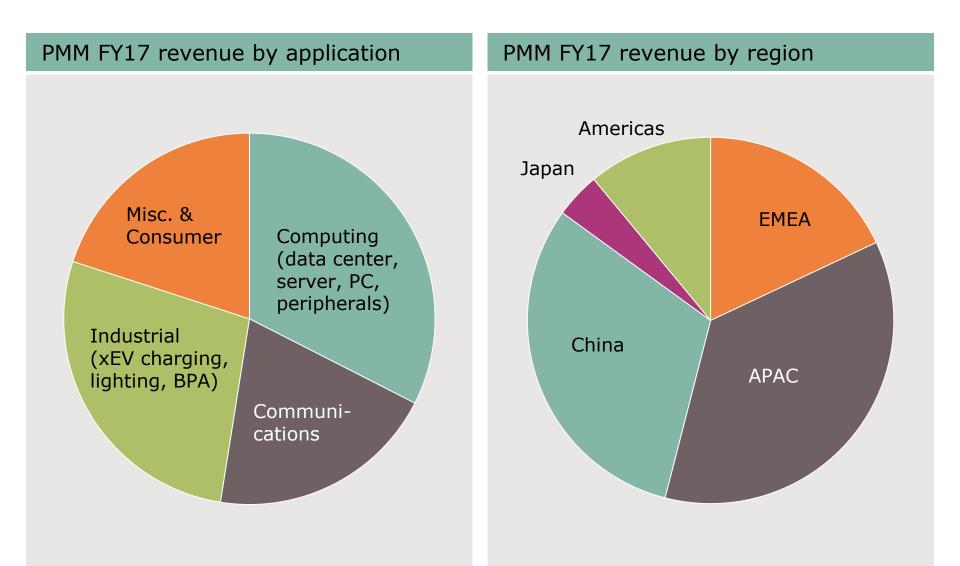


Part of your life. Part of tomorrow.



### Dashboard

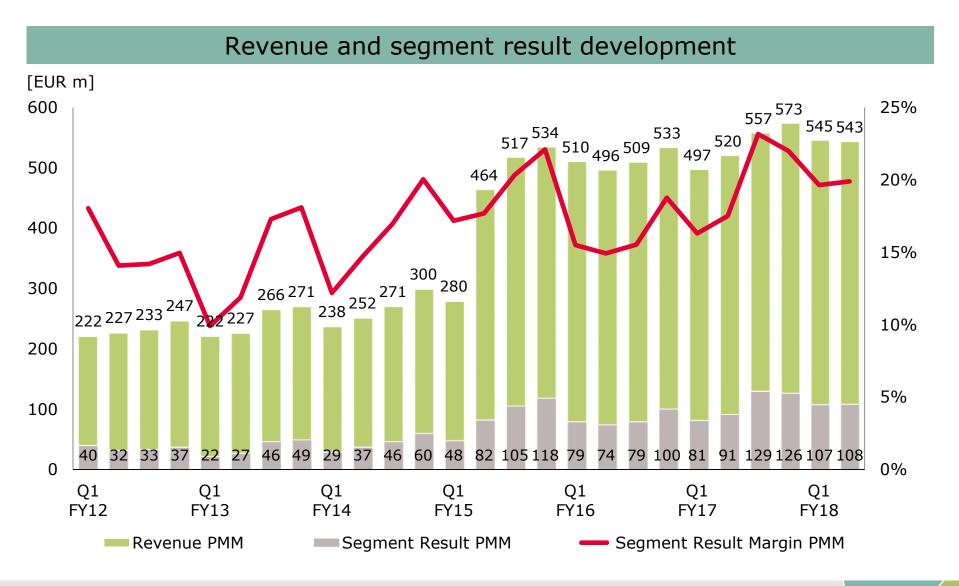




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## PMM historic financial figures

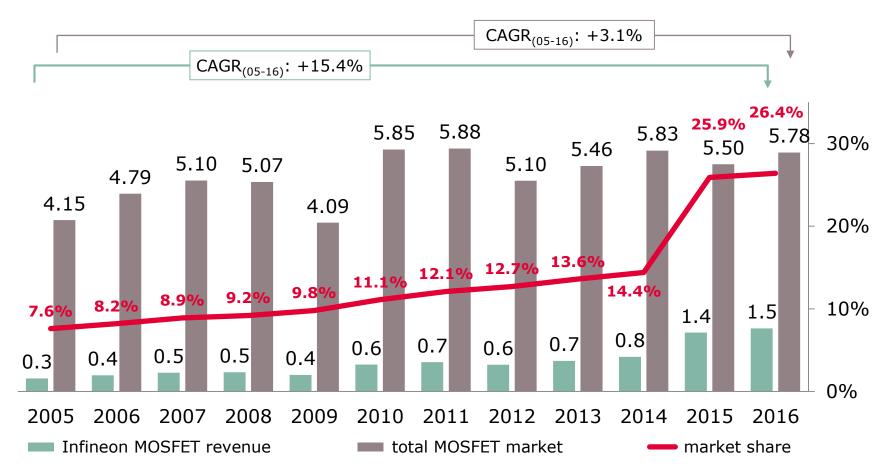


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## Continuous gain in market share in standard MOSFETs



Infineon's historic market share development 2005 – 2016



Source: Based on or includes content supplied by IHS Markit, Technology Group, several reports from 2004 through 2015 and 2017 Note: No backward revision of market shares and market sizes; except for year 2015

### Glossary



3D	three dimensional	MOSFET	metal-oxide silicon field-effect transistor
5G	fifth generation of cellular infrastructure standard	nm	nanometer
AC-DC	alternating current – direct current	OBC	on-board computer
AI	artificial intelligence	opex	operational expenditure
AR	augmented reality	PoL	point-of-load
capex	capital expenditure	PV	photovoltaic
CPU	central processing unit	RF	radio frequency
DC-DC	direct current – direct current	Rx	receiver
ECU	electronic control unit	Si	silicon
EV	electric vehicle	SW	software
IC	integrated circuit	тсо	total cost of operations
iPoL	image processing line	ToF	time of light
IR	infrared		-
kWh	kilowatt hour	Tx	transmitter
LSEV	low-speed electric vehicle	VR	virtual reality
MEMS	micro electro-mechanical systems	VRM	voltage regulator module
MIMO	multiple input, multiple output	WBG	wide bandgap material
mmWave	millimeter wave	xEv	all degrees of vehicle electrification (EV, FHEV, PHEV)

## Andreas Urschitz, Division President Power Management & Multimarket





- since 2012: Division President Power Management & Multimarket (PMM)
- > 2011: Head of Distribution of the PMM Division
- > 2001 2011: several management positions within PMM Division
- Andreas Urschitz was born in Klagenfurt, Austria, in 1972. He holds a master's degree in Commercial Science from the Vienna University of Economics and Business.
- > He joined Infineon (Siemens AG until 1999) in 1995.



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